

### FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

### MAXIMUM RATINGS

Parameter	Symbol	Limit	Unit
Drain-source voltage	$V_{DS}$	60	V
Gate-source voltage	$V_{GS}$	$\pm 20$	
Continuous drain current ( $T_J = 150^\circ\text{C}$ )	$T_C = 25^\circ\text{C}$	$I_D$	0.99
	$T_C = 100^\circ\text{C}$		0.62
Pulse drain current <sup>1</sup>	$I_{DM}$	3	A
Maximum power dissipation	$T_C = 25^\circ\text{C}$	$P_D$	6.25
	$T_A = 25^\circ\text{C}$		0.725
Thermal resistance, junction to ambient	$R_{thJA}$	170	$^\circ\text{C}/\text{W}$
Thermal resistance, junction to case	$R_{thJC}$	20	
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

1. Pulse width limited by maximum junction temperature

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
<b>STATIC</b>						
Drain-source breakdown voltage	$V_{DS}$	$V_{DS} = 0\text{V}, I_D = 10\mu\text{A}$	60	75	-	V
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1\text{mA}$	0.8	1.7	2	V
		$V_{DS} = V_{GS}, I_D = 1\text{mA}$ $T_C = -55^\circ\text{C}$	-	-	2.5	
		$V_{DS} = V_{GS}, I_D = 1\text{mA}$ $T_C = 125^\circ\text{C}$	0.3	-	-	
Gate-body leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$ $V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA
		$V_{GS} = \pm 20\text{V}$ $V_{DS} = 0\text{V}$ $T_C = 125^\circ\text{C}$	-	-	$\pm 500$	
Zero gate voltage drain current	$I_{DSS}$	$V_{GS} = 0\text{V}$ $V_{DS} = 48\text{V}$	-	-	1	$\mu\text{A}$
		$V_{GS} = 0\text{V}$ $V_{DS} = 48\text{V}$ $T_C = 125^\circ\text{C}$	-	-	100	$\mu\text{A}$
On-state drain current	$I_{D(on)}$	$V_{GS} = 10\text{V}$ $V_{DS} = 10\text{V}$	-	2	-	A
Drain-source on-state resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 5\text{V}$ $I_D = 0.3\text{A}$	-	2	5	$\Omega$
		$V_{GS} = 10\text{V}$ $I_D = 1\text{A}$	-	1.3	3	
		$V_{GS} = 10\text{V}$ $I_D = 1\text{A}$ $T_C = 125^\circ\text{C}$	-	2.4	5.6	
Forward transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 7.5\text{V}, I_D = 0.525\text{A}$	170	350	-	mS
Diode forward voltage	$V_{SD}$	$I_S = 0.99\text{A}, V_{GS} = 0\text{V}$	0.7	0.8	1.6	V
<b>DYNAMIC</b>						
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$ $V_{DS} = 25\text{V}, f = 1\text{MHz}$	-	35	50	pF
Output capacitance	$C_{oss}$		-	25	40	
Reverse transfer capacitance	$C_{rss}$		-	7	10	

# 2N6660

## 60V N-CHANNEL MOSFET

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

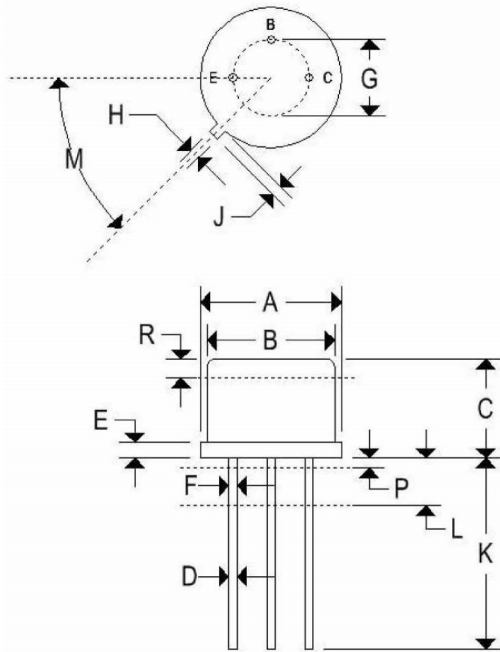
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Drain-source capacitance	$C_{ds}$		-	30	-	
<b>SWITCHING</b> <sup>b</sup>						
Turn-on time	$t_{ON}$	$V_{DD} = 25\text{V}, R_L = 23\ \Omega, I_D \sim 1\text{A}, V_{GEN} = 10\text{V}, R_g = 25\ \Omega$	-	8	10	nS
Turn-off time	$t_{OFF}$		-	8.5	10	

a. Pulse test:  $PW \leq 300\ \mu\text{s}$  duty cycle  $\leq 2\%$ .

b. Switching time is essentially independent of operating temperature.

**MECHANICAL CHARACTERISTICS**

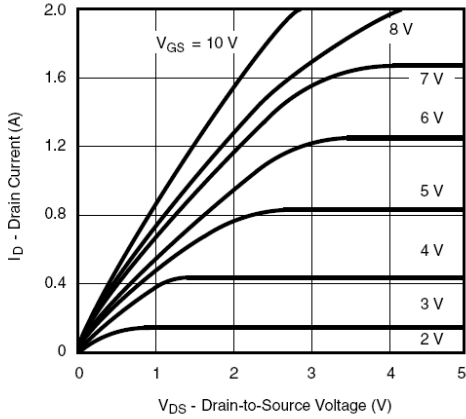
Case	TO-39
Marking	Alpha-numeric
Pin out	See below



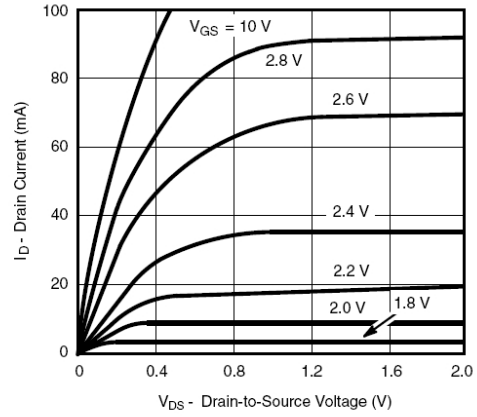
	TO-39			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.350	0.370	8.890	9.400
B	0.315	0.335	8.000	8.510
C	0.240	0.260	6.10	6.60
D	0.016	0.021	0.406	0.533
E	0.009	0.125	0.2269	3.180
F	0.016	0.019	0.406	0.533
G	0.190	0.210	4.830	5.33
H	0.028	0.034	0.711	0.864
J	0.029	0.040	0.737	1.020
K	0.500	-	12.700	-
L	0.250	-	6.350	-
M	45° NOM		45° NOM	
P	-	0.050	-	1.270
Q	90° NOM		90° NOM	
R	0.100	-	2.540	-

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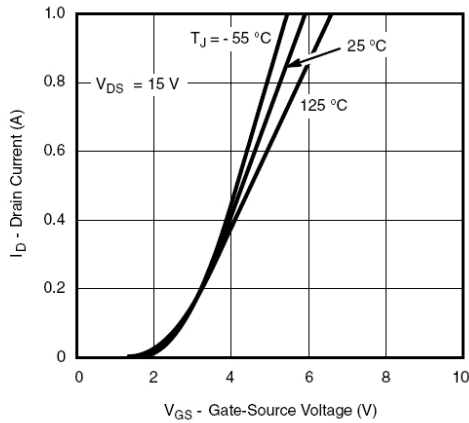
## 60V N-CHANNEL MOSFET



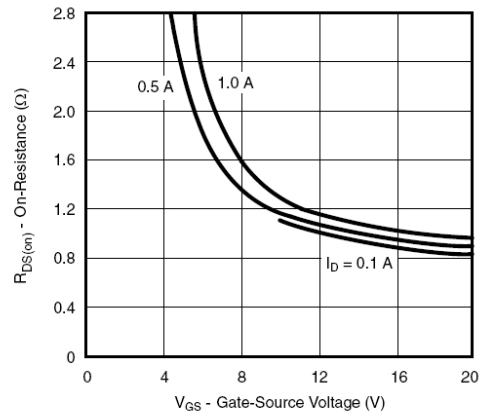
Ohmic Region Characteristics



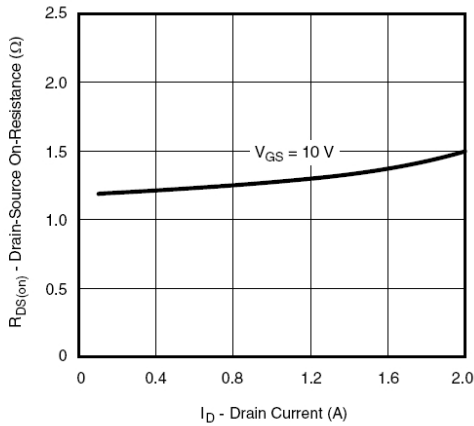
Output Characteristics for Low Gate Drive



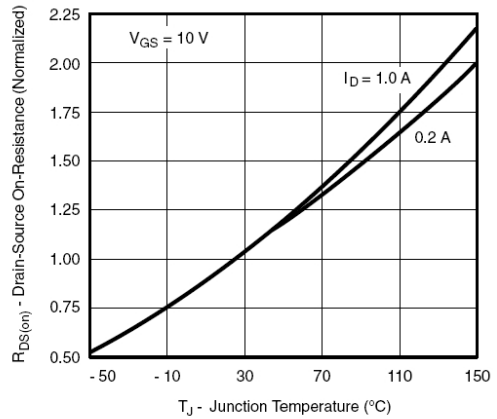
Transfer Characteristics



On-Resistance vs. Gate-to-Source Voltage



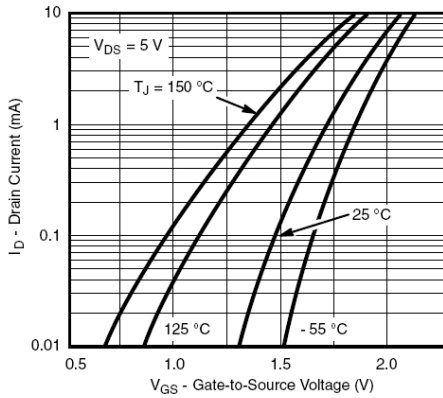
On-Resistance vs. Drain Current



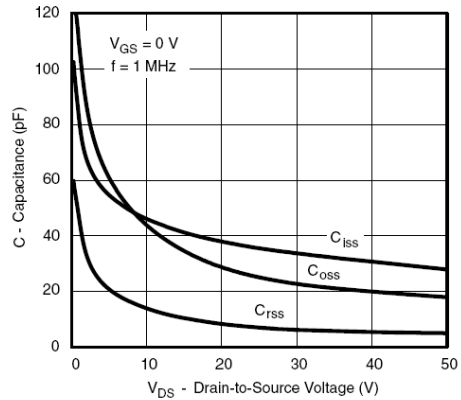
Normalized On-Resistance vs. Junction Temperature

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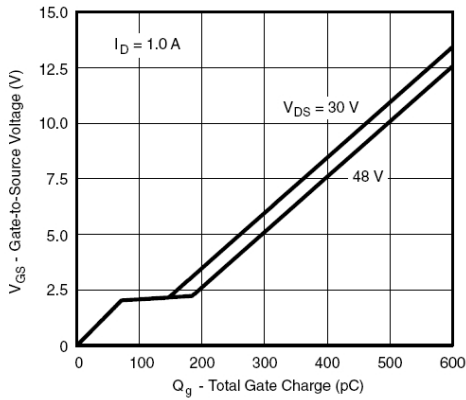
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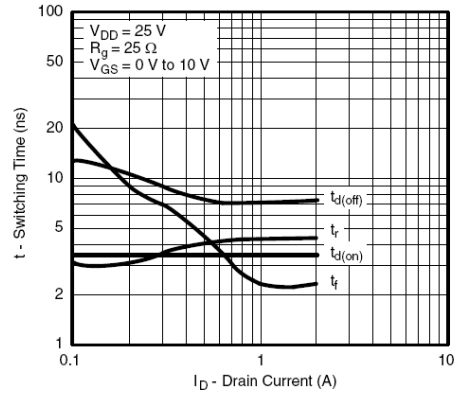
Threshold Region



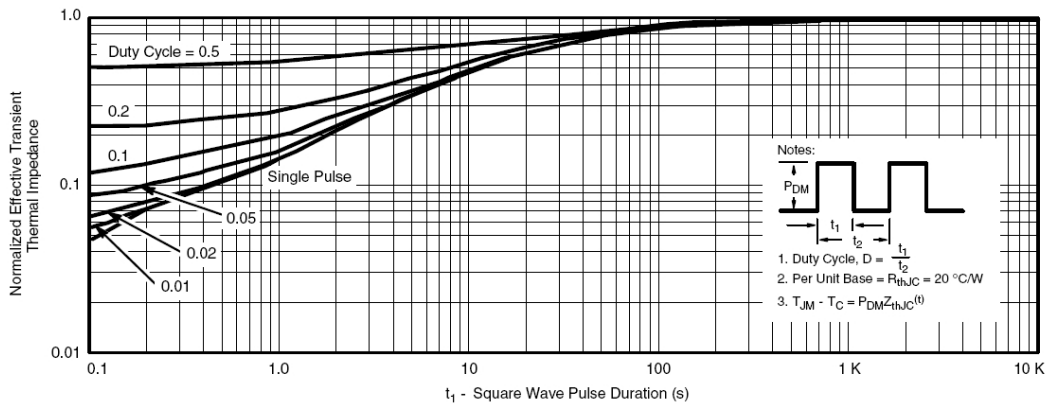
Capacitance



Gate Charge



Load Condition Effects on Switching



Normalized Thermal Transient Impedance, Junction-to-Ambient